Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

2SJ681

Relay Drive, DC-DC Converter and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance: RDS (ON) = 0.12Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0 \text{ S (typ.)}$
- Low leakage current: $IDSS = -100 \mu A \text{ (max) (VDS} = -60 \text{ V)}$
- Enhancement mode: $V_{th} = -0.8 \text{ to } -2.0 \text{ V}$

$$(V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$$

Maximum Ratings (Ta = 25°C)

| Characteris | stics | Symbol | Rating | Unit |
|-------------------------|------------------------|------------------|---------|------|
| Drain-source voltage | | V_{DSS} | -60 | V |
| Drain-gate voltage (R | _{SS} = 20 kΩ) | V_{DGR} | -60 | V |
| Gate-source voltage | | V _{GSS} | ±20 | V |
| Drain current | DC (Note 1) | I _D | -5 | Α |
| | Pulse(Note 1) | I_{DP} | -20 | Α |
| Drain power dissipation | ו | P_{D} | 20 | W |
| Single pulse avalanche | e energy (Note 2) | E _{AS} | 40.5 | mJ |
| Avalanche current | | I _{AR} | -5 | Α |
| Repetitive avalenche e | nergy (Note 3) | E _{AR} | 2 | mJ |
| Channel temperature | | T _{ch} | 150 | °C |
| Storage temperature ra | ange | T _{stg} | -55~150 | °C |

0.8 MAX 1. GATE 2. DRAIN (SOURCE SINK) 3. SOURCE JEDEC JETA

2-7J2B

Weight: 0.36 g (typ.)

TOSHIBA

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 6.25 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 125 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = -25 V, T_{ch} = 25°C (initial), L = 2.2 mH, R_G = 25 Ω , I_{AR} = -5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

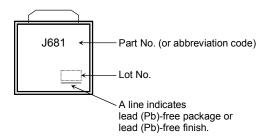
Electrical Characteristics (Ta = 25°C)

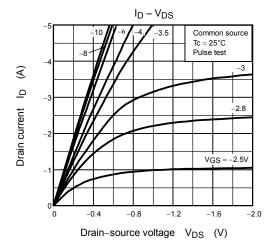
| Charac | eteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|---------------|----------------------|---|------|------|------|------|
| Gate leakage cu | rrent | I _{GSS} | V _{GS} = ±16 V, V _{DS} = 0 V | _ | _ | ±10 | μA |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = -60 V, V _{GS} = 0 V | 1 | _ | -100 | μA |
| Drain-source breakdown voltage | | V (BR) DSS | $I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$ | -60 | _ | _ | V |
| | | V (BR) DSX | $I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$ | -35 | _ | _ | V |
| Gate threshold v | roltage | V _{th} | V _{DS} = -10 V, I _D = -1 mA | -0.8 | _ | -2.0 | V |
| Drain-source ON resistance | | Dec (c) | $V_{GS} = -4 \text{ V}, I_D = -2.5 \text{ A}$ | _ | 0.16 | 0.25 | Ω |
| | | R _{DS} (ON) | V _{GS} = -10 V, I _D = -2.5 A | _ | 0.12 | 0.17 | |
| Forward transfer | admittance | Y _{fs} | V _{DS} = -10 V, I _D = -2.5 A | 2.5 | 5.0 | _ | S |
| Input capacitance | | C _{iss} | | _ | 700 | _ | pF |
| Reverse transfer capacitance | | C _{rss} | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | _ | 60 | _ | |
| Output capacitance | | Coss | | | 90 | _ | |
| Switching time | Rise time | t _r | V_{GS} -10 V CI $RL = 12 \Omega$ $V_{DD} \approx -30 \text{ V}$ | _ | 14 | _ | |
| | Turn-on time | t _{on} | | _ | 24 | _ | ns |
| | Fall time | t _f | | ı | 14 | _ | |
| | Turn-off time | t _{off} | Duty ≦ 1%, t _W = 10 μs | | 95 | _ | |
| Total gate charge (Gate-source plus gate-drain) | | Qg | | | 15 | | nC |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$ | | 11 | _ | |
| Gate-drain ("miller") charge | | Q_{gd} | | _ | 4 | _ | |

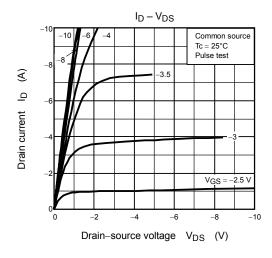
Source-Drain Ratings and Characteristics (Ta = 25°C)

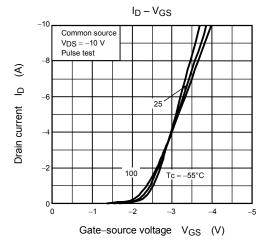
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|-----|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | | _ | -5 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | | _ | -20 | Α |
| Forward voltage (diode) | V _{DSF} | I _{DR} = -5 A, V _{GS} = 0 V | _ | _ | 1.7 | V |
| Reverse recovery time | t _{rr} | I _{DR} = -5 A, V _{GS} = 0 V | - | 40 | _ | ns |
| Reverse recovery charge | Qrr | dl_{DR} / $dt = 50 A / \mu S$ | | 32 | _ | nC |

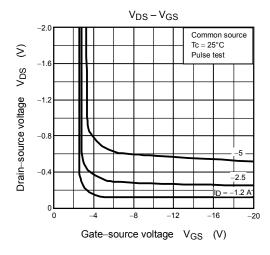
Marking

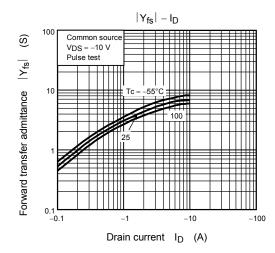


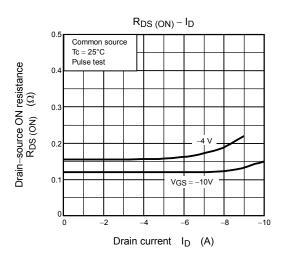




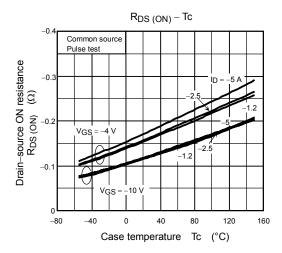


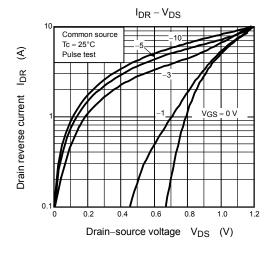


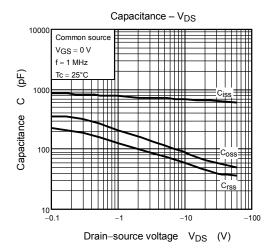


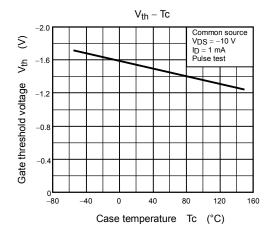


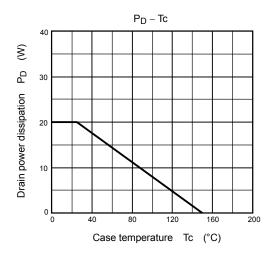
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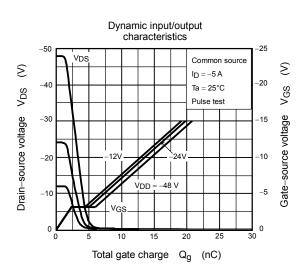


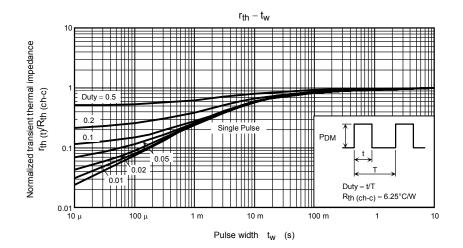


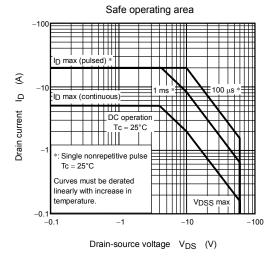


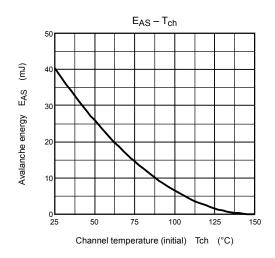


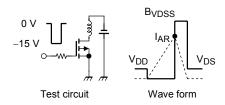












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= -25~V,~L = 2.2~mH \end{aligned}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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